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# Product Change Notification - KSRA-11JPBE431 (convert To PDF)

Date:

05 Jun 2018

**Product Category:** 

**Ethernet PHYs** 

**Affected CPNs:** 



# **Notification subject:**

CCB 2672.002 and CCB 2672.003 Initial Notice: Qualification of ASE as a new assembly site for selected products of the 110nm wafer technology at DBHU available in 24L VQFN(4X4X0.9mm) and 32L VQFN(5X5X0.9mm) packages using palladium coated copper wire with gold flash (CuPdAu) bond wire.

#### **Notification text:**

#### **PCN Status:**

Initial notification

#### **PCN Type:**

Manufacturing Change

## **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

#### **Description of Change:**

Qualification of ASE as a new assembly site for selected products of the 110nm wafer technology at DBHU available in 24L VQFN(4X4X0.9mm) and 32L VQFN(5X5X0.9mm) packages using palladium coated copper wire with gold flash (CuPdAu) bond wire

## **Pre Change:**

Assembled at TICP using silver (Ag) bond wire

## **Post Change:**

Assembled at ASE using palladium coated copper wire with gold flash (CuPdAu) bond wire.

# **Pre and Post Change Summary:**

	Pre Change	Post Change			
Assembly Site	Taiwan IC Packing Corp (TICP)	ASE Inc (ASE)			
Wire material	Ag	CuPdAu			
Die attach material	EN4900	EN4900			
Molding compound material	G631	G631			
Lead frame material	C194	C194			

None

# **Change Impact:**

None

# **Reason for Change:**

To improve manufacturability by qualifying ASE as new assembly site

# **Change Implementation Status:**

In Progress

# **Estimated Qualification Completion Date:**

November 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

# **Time Table Summary:**

	June 2018				<b>&gt;</b>	November 2018 →					
Workweek	22	23	24	25	26		44	45	46	47	48
Initial PCN Issue Date		Χ									
Qual Report Availability											X
Final PCN Issue Date											X

#### **Method to Identify Change:**

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

#### **Revision History:**

June 05, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachment(s):

PCN\_KSRA-11JPBE431\_Qual\_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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